

# **SPECIFICATION FOR APPROVAL**

(3) Any changes to these specific Product Specification Sheet wil (4) Any issuance of purchase ord	der prior to consigning back the Approval page of "Specification Sheets" as the agreement on the contents of these specifications.
(3) Any changes to these specific Product Specification Sheet wil (4) Any issuance of purchase ord from customers will be regarde	der prior to consigning back the Approval page of "Specification Sheets" as the agreement on the contents of these specifications.
(3) Any changes to these specific Product Specification Sheet wil (4) Any issuance of purchase ord	der prior to consigning back the Approval page of "Specification Sheets"
(3) Any changes to these specific Product Specification Sheet will	
(3) Any changes to these specific	
	cations must be agreed upon by both parties and new revision of the
(2) Orders received and accepted by these specifications.	y EAS after return of signed copy of specification will be produced per
of the attached specifications.	with signature and title of authorized individual that signifies acceptance
CUSTOMER SIGNA	ATURE & Date
DATE	:
PM / SALES	:
CUSTOMER P/N	•
REVISION	
EAS P/N	: EAS49SMD11.059K0DJR1
NOMINAL FREQ.	: 11.059200MHz
FRODUCTTIFE	: HC-49/S SMD
PRODUCT TYPE	•





# PRODUCT SPECIFICATION SHEET

PRODUCT TYPE : HC-49/S SMD

NOMINAL FREQ. : 11.059200MHz

EAS P/N : EAS49SMD11.059K0DJR1

REVISION : A3

PE/RD	QA	MFG

#### NOTE:

- (1) The green product standard set by EAS is based upon the international standards. Related information is publicly described on the EAS's Website, and updated regularly. The document is compliant with the latest green product quality system directives at the time.
- (2) Revision "Sx" is for engineering samples only. PE/RD's approval required.
- (3) Revision "Ax" is production ready. PE, QA and MFG's approval required.

**RoHS Compliant** 

EAS CORPORATION EAS P/N: EAS49SMD11.059K0DJR1 A3

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<u>Rev</u>	Revise page	Revise contents	<u>Date</u>	Ref.No.	<u>Reviser</u>
A1	N/A	Initial Released	2018/10/7	N/A	Allen SU

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# ATTACHMENT(S) (optional)

# **TESTING DATA**

ELECTRICAL CHARACTERISTICS TEST	A□ YES☑ NO
TEMPERATURE CHARACTERISTICS TEST	B□ YES☑ NO

#### **ELECTRICAL SPECIFICATIONS**

### Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature :  $25+/-5^{\circ}C$ Relative humidity :  $40\%\sim70\%$ 

If there is any doubt about the results, measurement shall be made within the following limits:

Ambient temperature :  $25+/-1^{\circ}C$ Relative humidity :  $40\%\sim70\%$ 

#### Measure equipment

SAUNDERS 250A/250B CRYSTAL IMPEDANCE METER.

#### Crystal cutting type

The crystal is using AT CUT (thickness shear mode).

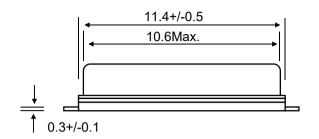
	Parameters			Electric	cal		Notes
			MIN.	TYP.	MAX.	UNITS	
1	Nominal Frequency	FL	1	1.059200 MH	łz	MHz	
2	Oscillation Mode			Fundamental			
3	Load Capacitance	CL		20.0		pF	
4	Frequency Tolerance	FT	-20		+20	ppm	at 25 °C +/- 3 °C
5	Frequency Tolerance	ST	-30		+30	ppm	Over Operating Temp.Range
6	Operating Temperature	OT	-20		+70	°C	
7	Aging		-5		+5	ppm	1st year
8	Drive level	DL		100	500	uW	
9	Effective Resistance Rr	Rr			70	ohm	
10	Shunt Capacitance	C0			7	pF	
11	Motional Capactiance	C1				fF	
12	Insulation Resisstance		500			Mohm	at DC 100V
13	Storage Tempeature Range		-40		+85	°C	
14	SPDB(+/-5000ppm)				-3.0	dB	

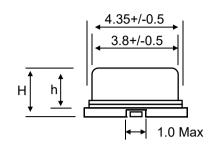
■ FACTORY LOCATION : CHINA

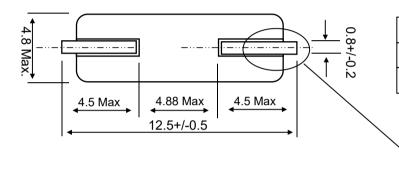
# **DIMENSIONS**

# UNIT:mm

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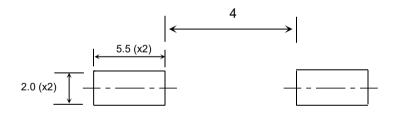




CHOOSE	TYPE	H(SMDHIGH)	h(BODY HIGH)
	S3	3.8+/-0.3	3.3+/-0.3
	S2	3.0+/-0.3	2.3+/-0.3

**Suggested Layout** 

Solder Coating (Sn-Ag-Cu Pb Free Coating)



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#### **■ SUGGESTED REFLOW PROFILE**

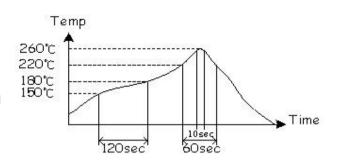
Solder melting point :220+/-10 °C, 60 sec. Min. Peak Temperature: 260 +/- 5 °C, 10 sec. Max.

### ■ SUGGESTED MANUAL SOLDER CONDITION

Temperature: 350 +/- 10 °C

Time: 3 sec.

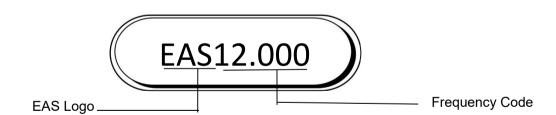
Re-solder times: twice



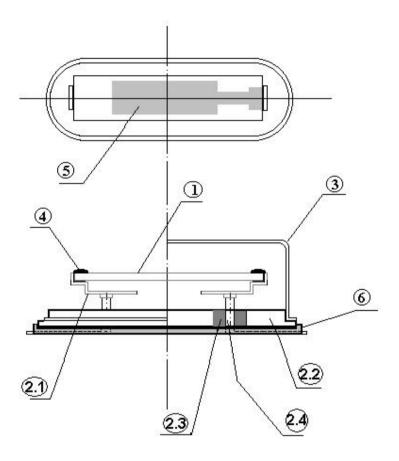
# Marking

Unit Weight: 0.58 g +/- 0.05g





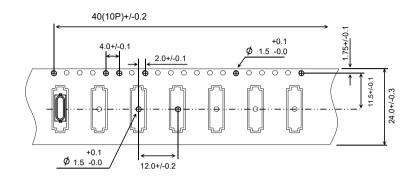
# **STRUCTURE ILLUSTRATION:**

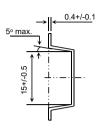


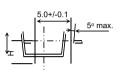
N	10	COMPONENTS		MATERIALS	FINISH/SPECIFICATIONS		
	1	CRYSTAL BLANK		QUARTZ (SiO <sub>2</sub> )	I		
	2.1		SUPPORTER	NICKEL SILVER	I		
	2.2		HOLDER	SPCC	Ni PLATED		
2	2.3	CRYSTAL BASE	GLASS	GLASS	I		
	2.4		DAGE		LEAD	KOVAR	Ni PLATED+SOLDER DIPPED
			LEAD	KOVAK	(Coating : Sn/Ag/Cu)		
,	3	CRYSTAL C	OVER	NICKEL SILVER	Ni PLATED		
4	4	CONDUCTIVE ADHESIVE		Ag + RESIN	I		
	5	ELECTRODE		Noble Metal	I		
(	6	INSULATION PAD		PPS	I		

# (A) Tape and reel configuration:(Unit: mm)

(a) Emboss taping configuration. (per EIA-481-2)





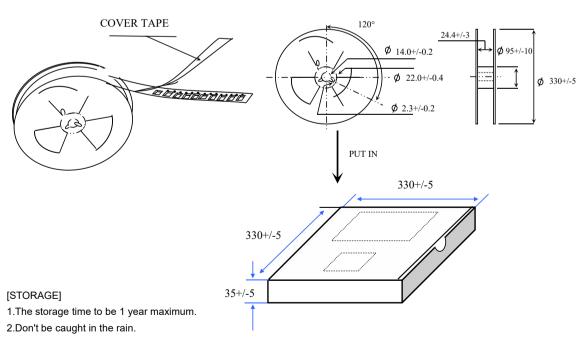


	Direction of sta	art	COVER TAPE
NONE	Products put in 1000 pcs Max.	NONE	l
			22.0 Max.
← 160 Min.	•	160 Min.	
		390 Min.	230 Min.

TYP. H (+/-0.2) S3 4.35 S2 3.5

(b) Reel configuration.

# (B) Packing & Label :(Unit: mm)



- 3. The storage environment shall be  $5^{\circ}$ C  $\sim$ 40 $^{\circ}$ C temperature and 30%  $\sim$  75%RH humidity and free from the sun shine.
- 4.If customers have special requirements, we can paste labels according to it.

# **■ RELIABILITY SPECIFICATIONS**

#### 1.Mechanical Endurance

No.	Test Item	Test Methods		Test Criteria	
1.1	Drop test	50 cm Height, Fall freely onto firm wo	od for 3 times.	ВС	
1.2	Mechanical Shock	1000 G , 0.5 m Sec. , 3 times for all	3 directions.	ВС	
		Frequency range	10 ~ 2000 Hz		
			Acceleration	5G	
1.3	Vibration	Sweep time	20 minute	ВС	
		Pendicular axes each test time	4 hours		
			(Total test time 12 hours)		
1.4	Terminal Strength	17.7N force for 60sec +/-1sec.		F	
1.5	Coldorability	Pb free :Temperature 235+/-5°C,Imme	ersion time:5+/-1sec	E	
1.3	Solderability	Pb :Temperature 215+/-5°C,Immersion time:5+/-1sec		E	

#### 2.Environmental Endurance

No.	Test Item	Test Methods	SPEC
2.1	Resistance To Soldering Heat	Test temperature 260 +/- 5 °C  Test time 10 +/- 1 sec.  Emersion Rate 25 +/- 6 mm/s  Immersed of specimen 1.5mm	ACD
2.2	High Temp. Storage	+ 85°C +/- 3 °C for 500 +/- 12 Hrs	ACD
2.3	Low Temp. Storage	- 40 °C +/- 3 °C for 500 +/-12 Hrs	ACD
2.4	Temperature cycle	-40°C~85°C, for 300 cycles.  1 cycle  25 °C  -40+/-3 °C  30 min.  5 min.	ACD
2.5	High Temp & Humidity	85°C +/- 3°C , RH 85% , 500 Hrs	ACD

# **■**HANDING CAUTIONS

Prohibit the use of ultrasonic welding in Assemblying

0 0

### **RELIABILITY SPECIFICATIONS**

Specifica	Specifications				
А	Frequency change: Within +/-20ppm or in customer's specification.				
В	Frequency change: Within +/-10ppm or in customer's specification.				
С	Equivalent series resistance(E.S.R) change: Within +/-15% or 10Ω(larger value).				
D	After conditioning , quartz crystal units shall be subjected to standard atmospheric conditions for 24 hour, and measured.				
Е	Minimum 95% of immersed terminal shall be covered with new uniform solder.				
F	No damage on specimen				

### **Measurement condition**

Measurements are carried out with Network-analyzer( S&A 250B or equivalent).